

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently Amended) A method for forming a pattern over a substrate for a liquid crystal display device, comprising:

providing a substrate having an etching layer formed thereon;

locating a master having at least one opening in on the etching layer, the master having at least one opening;

filling filling a resist in the at least one opening of the master; and

separating the master from the substrate to leave the resist on the substrate.

2. (Original) The method of claim 1, wherein the filling a resist in the at least one opening of the master comprises:

contacting a resist supplying roll to the master; and

filling the resist in the at least one opening of the master by rotating the resist supplying roll over the at least one opening of the master.

3. (Original) The method of claim 1, wherein the filling a resist in the at least one opening of the master comprises:

applying the resist on the master; and

planarizing the applied resist on the surface of the master by using a doctor blade.

4. (Original) The method of claim 1, wherein the master is separated apart from the substrate by a few micrometers (μm).
5. (Original) The method of claim 1, wherein the etching layer is a metal layer.
6. (Original) The method of claim 1, wherein the etching layer is an insulating layer.
7. (Original) The method of claim 6, wherein the insulating layer is formed of one of SiO_x or SiN_x.
8. (Original) The method of claim 1, wherein the etching layer is a semiconductor layer.
9. (Original) The method of claim 1, further comprising hardening the resist.
10. (Currently Amended) A method for forming a pattern over a substrate for a liquid crystal display device, comprising:
 - providing a substrate having an etching layer formed thereon;
 - placing a master having at least one opening on an area corresponding to the etching layer to be etched;
 - applying a resist on the master;

planarizing the applied resist on the surface of the master and filling the resist in the at least one opening by using a doctor blade;

hardening the planarized resist; and

forming a resist pattern on the etching layer by separating the master from the substrate.

11. (Original) The method of claim 10, wherein the master is separated apart from the substrate by a few micrometers (μm).

12. (Currently Amended) A method for forming a pattern over a substrate for a liquid crystal display device, comprising:

providing a substrate having an etching layer formed thereon;

placing a master having at least one opening corresponding to the etching layer to be etched;

contacting a resist supplying roll on the master to fill the resist in the at least one opening of the master;

hardening the filled resist in the at least one opening of the master; and

forming a resist pattern on the etching layer by separating the master from the substrate.

13. (Original) The method of claim 12, wherein the master is separated apart from the substrate by a few micrometers (μm).